



PK740 (v1.0) May 29, 2015

100% Material Declaration Data Sheet Spartan®-6 Cu Wire CS324 Package

Average Weight: 0.6889 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.022310	3.238%
	Silicon	7440-21-3	100.00	Main material	0.022310	
Die Attach Material					0.007051	1.023%
	Silver	7440-22-4	77.50	Main material	0.005465	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.001058	
	Acrylate monomer	Trade Secret	7.50	Main material	0.000529	
Copper Wire					0.002454	0.356%
	Cu	7440-50-8	98.25	Main material	0.002411	
	Pd	7440-05-3	1.75	Dopant	0.000043	
Mold Compound					0.214577	31.147%
	Epoxy Resin	Trade secret	7.50	Main material	0.016093	
	Phenol Resin A	9003-35-4	3.00	Main material	0.006437	
	Phenol Resin B	Trade secret	3.00	Main material	0.006437	
	Silica(Amorphous) A	60676-86-0	67.95	Filler	0.145805	
	Silica(Amorphous) B	7631-86-9	15.00	Filler	0.032187	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.006437	
	Carbon black	1333-86-4	0.55	Color agent	0.001180	
Solder Balls					0.130099	18.885%
	Tin (Sn)	7440-31-5	63.00	Main material	0.081962	
	Lead (Pb)	7439-92-1	37.00	Main material	0.048137	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					0.312424	45.350%
	Au	7440-57-5	1.33	Main material	0.004153	
	Ni	7440-02-0	9.43	Main material	0.029465	
	Cu plating	7440-50-8	18.89	Plating	0.059015	
	Continuous Filament Fiber Glass	65997-17-3	16.34	Glass Fiber	0.051049	
	BT Core	7440-50-8 N/A	49.02	Core	0.153148	
Solder Mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6 N/A	4.99	Solder mask	0.015593		

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/29/15	1.0	Initial Xilinx release

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